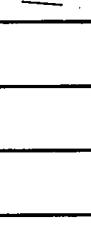


INFORMATION DISCLOSURE CITATION <i>(Use several sheets if necessary)</i>				Docket Number (Optional) 71711-8		Application Number To be assigned		
				Applicant(s) Tai Chung CHAI et al.		Filing Date Concurrently Herewith		Group Art Unit To be assigned
U.S. PATENT DOCUMENTS								
*EXAMINER INITIAL	REF	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE	
CC		4,924,291		Lesk et al.	—	—		
 JC 564 U S 497421 PRO 02/07/00								
FOREIGN PATENT DOCUMENTS								
	REF	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
							YES	NO
								
OTHER DOCUMENTS <i>(Including Author, Title, Date, Pertinent Pages, Etc.)</i>								
CC		Umehara, Norito et al., S-Pad Implementation; Total Plastic Package Crack Solution for Non-Moisture Sensitive Pakcage, New Package Development, Texas Instruments Japan, Ltd., Hi j. i. Plant, 4260 takao, Kawasaki, Hiji-machi, Hayami-gun Oita Japan 879-15						
U	~	Ganesan, Gans S. et al., Level I CrackFree Plastic Packaging Technology, Motorola Inc.. Semiconductor Products Sector, 2100 E. Elliot Road, Tempe, AZ 85284						
EXAMINER 				DATE CONSIDERED <i>7-11-01</i>				

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INFORMATION DISCLOSURE CITATION

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Docket Number (Optional)

3928/71711-2/8

Application Number

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Applicant(s)

Tai Chung CHAI

Filing Date

Concurrently Herewith

Group Art Unit

To be assigned

*EXAMINER
INITIAL

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

CC 2 Nakazawa, Tsutomu et al., A Novel Structure to Realize Crack-Free Plastic Packages During Reflow Soldering Process-Development of Chip Side Support (CSS) Package, IEEE Transactions on Components Packaging and Manufacturing Technology - Part C, Vol. 19, No. 1, January 1996, pp. 61-69.

1 1 Chan, K. C. and Chai, T. C., Type II Popcorn Failure Analysis in Plastic Encapsulated IC Package Using Scanning Acoustic Microscopy and Cross-Sectioning (not yet published)

✓ 1 CHA, Ki-Bon et al.; Ultra-Thin and Crack-Free Bottom Leaded Plastic (BLP) Package Design; LG Semicon (Gold Star) Package R&D Center, Cheongju, Korea 360-480 0569-5503/95/0000 © 1995 IEEE

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